

REMARKS

Originally filed claims 1-3, 6, 9, 10-18 were rejected under 35 U.S.C § 103(a) as obvious over Iijima et al. (U.S. Patent No. 6,828,221) in view of Asahi et al. (U.S. Patent Application No. 2002/0135058).

Claims 1-18 have been canceled and replaced by new claims 19-30.

Independent claim 19 of the present application recites a method for manufacturing a circuit device that comprises a supporting conductive substrate, a first and second wiring layer and a barrier film, where the supporting conductive film is “thoroughly removed” to expose the barrier film. In the disclosed example, the supporting conductive substrate is identified by reference numeral 12, the first and second wiring layers are identified, respectively as 11A and 11B, and the barrier film is identified by 13.

The Iijima et al. patent discloses a method for manufacturing a wiring circuit substrate 33 comprising conductor circuits 31, 32, insulating layer 27, nickel etching barrier 22 and protrusions 25 formed from copper foil (*see* FIGS. 1-4). The Asahi et al. patent application discloses a method for forming a component built-in module, which includes sealing a semiconductor element with sealing resin.

Contrary to the method recited in claim 19 of the present application, Iijima et al. does not disclose a step in which a supportive conductive film is “*thoroughly*” removed to “*expose the barrier film.*” Instead, as shown in FIGS. 2C-2D of Iijima et al., the copper foil 23 on the bottom of multilayer body 30A is etched to form conductor circuit 32 but is not thoroughly removed to expose the nickel etching barrier layer 22. The nickel-etching barrier layer 22 *remains covered* by the conductor circuit 32 (i.e., the portion of the copper foil 23 that is not removed by the etching).

Furthermore, as shown in FIGS. 3E-3F of Iijima et al., both the nickel etching barrier layer 22 and copper foil 23 are etched so that copper foil 23 forms conductor circuit 32. Although small regions on the sides of the etched nickel etching barrier layer 22 are exposed (*see*

FIG. 3F), the copper foil 23 is not *thoroughly* removed. Thus, the Iijima et al. patent does not disclose or suggest claim 19 of the present application. Furthermore, the Asahi et al. patent application does not disclose or suggest thoroughly removing a supporting conductive film to expose a barrier film. Therefore, combining the cited references would not disclose or suggest claim 19 of the present application.

Likewise, independent claim 26 recites that the supporting conductive film is removed *entirely*. As noted above, Iijima et al. discloses a copper foil 23 that is not entirely removed in forming conductor circuit 32 for multilayer body 33A or multilayer body 33B (*see* FIGS. 2-3). Instead, the metal layer 23 is *partially* etched using resist films 24 as etching masks to *leave a patterned metal film* forming conductor circuit 32 (col. 25, lines 24-28; col. 27, lines 5-20). Thus, neither the Iijima et al. patent alone nor in combination with Asahi et al. discloses or suggests claim 26 of the present application.

Additionally, dependent claims 24 and 30 of the present application recite that the “supporting conductive film is thicker than a conductive film material for the first wiring layer.” In contrast, the copper foil 23 of Iijima et al. is thinner than the copper foil 21 (col. 24, lines 14-22).

Furthermore, the Hayashi, Yamamoto and Kishida references do not disclose or suggest the claimed subject matter individually or in combination with the Iijima and Asahi references.

At least for the foregoing reasons, claims 19-30 should be allowed.

It is believed all of the pending claims have been addressed. However, the absence of a reply to a specific rejection, issue or comment does not signify agreement with or concession of that rejection, issue or comment. In addition, because the arguments made above may not be exhaustive, there may be reasons for patentability of any or all pending claims (or other claims) that have not been expressed. Finally, nothing in this paper should be construed as an intent to concede any issue with regard to any claim, except as specifically stated in this paper, and the amendment of any claim does not necessarily signify concession of unpatentability of the claim prior to its amendment.

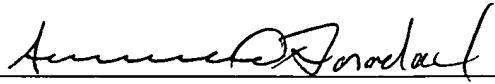
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Serial No. : 10/667,771
Filed : September 22, 2003
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Attorney's Docket No.: 14225-024001 / F1030479US00

Please apply any charges or credits to deposit account 06-1050.

Respectfully submitted,

Date: 12/15/05



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